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2826  
PATENTS  
112055-0040



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#17  
C.A.

In Re The Application of:  
David Chong et al.

Serial No.: 09/823,600

Filed: March 30, 2001

For: PACKAGING SYSTEM FOR DIE-  
UP CONNECTION OF A DIE-  
DOWN ORIENTED INTEGRATED  
CIRCUIT

Examiner: Not yet assigned

Art Unit: Not yet assigned

Cesari and McKenna, LLP  
88 Black Falcon Avenue  
Boston, MA 02210  
May 1, 2002

**CERTIFICATE OF MAILING**

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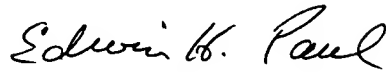
Pursuant to 37 C.F.R. §1.33(a), we request that the correspondence address for the above-identified patent application be changed to:

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No. 03-1237.

Respectfully submitted,



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